TOSHIBA LED LAMP GaP GREEN LIGHT EMISSION

TLGC180AP

PANEL CIRCUIT INDICATOR

Striking Bright Green

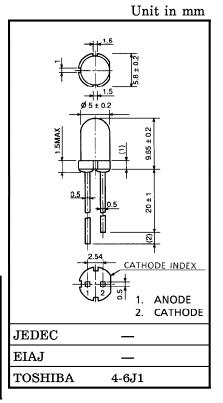
All Plastic Mold Type Colorless Clear Lens

Low Drive Current, High Intensity Green Light Emission. Recommended Forward Current: IF=15~20mA (DC)

- All Plastic Molded Lens, Provides an Excellent ON-OFF Contrast Ratio.
- Fast Response Time, Capable of Pulse Operation.
- Without stand-offs

MAXIMUM RATINGS (Ta = 25°C)

CHARACTERISTIC	SYMBOL	RATING	UNIT
Forward Current (DC)	$I_{\mathbf{F}}$	40	mA
Reverse Voltage	v_{R}	4	V
Power Dissipation	$P_{\mathbf{D}}$	120	mW
Operating Temperature Range	$T_{ m opr}$	-20~85	°C
Storage Temperature Range	$ m T_{stg}$	-30~100	$^{\circ}\mathrm{C}$



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ELECTRO-OPTICAL CHARACTERISTICS (Ta = 25°C)

СНАН	RACTERISTIC	SYMBOL	TEST CONDITION	MIN.	TYP.	MAX.	UNIT
Forward V	oltage	$ m V_{ m F}$	$I_{\mathbf{F}} = 20 \text{mA}$	_	2.15	2.8	V
Reverse Cu	arrent	${ m I}_{ m R}$	$V_R=4V$	_	_	5	μ A
Luminous Intensity	TLGC180AP			85	300	_	
	TLGC180AP (NP)	$_{ m I_{ m V}}$	$I_F = 20 \text{mA}$ (Note)	85	_	414	mcd
	TLGC180AP (PQ)			153	_	736	
Peak Emission Wave Length		$\lambda_{ m p}$	$I_{\mathbf{F}} = 20 \text{mA}$		567	_	nm
Spectral Li	ine Half Width	Δλ	$I_{\mathbf{F}} = 20 \text{mA}$	_	25	_	nm

(Note) Rank selection carried out under next standard range respectively, although it needs ±15% additionary for guaranteed limits.

N:100~200mcd

P:180~360mcd

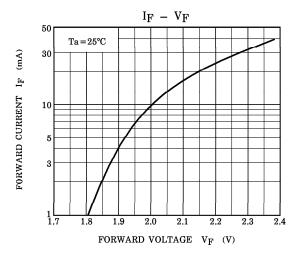
 $Q:320\sim640$ mcd

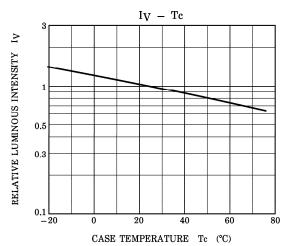
Each rank products is classified by package unit, and (NP) includes N and P, (PQ) includes P and Q.

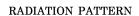
PRECAUTION

Please be careful of the followings.

- Soldering temperature: 260°C MAX. Soldering time: 3s MAX. (Soldering portion of lead: up to 2mm from the body of the device)
- If the lead is formed, the lead should be formed up to 5mm from the body of the device without forming stress to the resin. Soldering should be performed after lead forming.







Ta = 25°C

